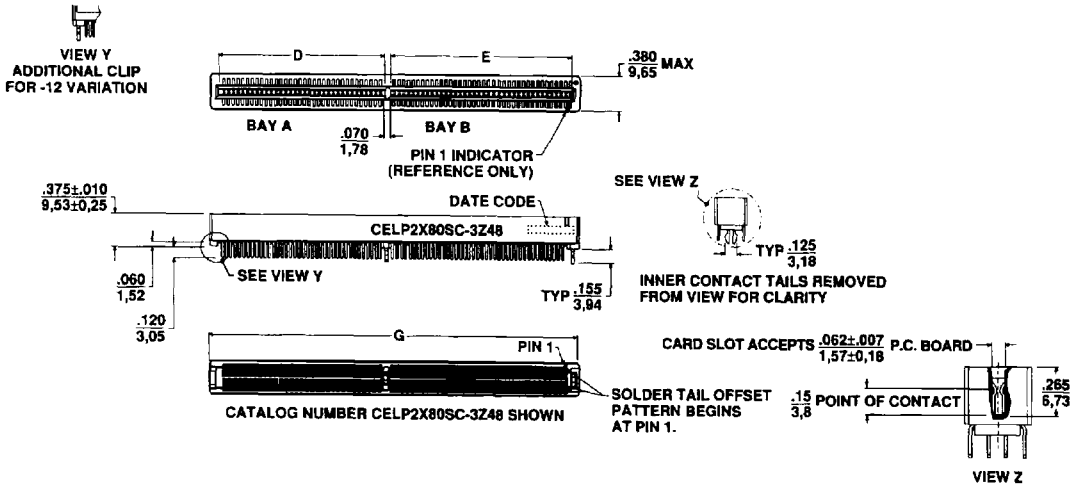


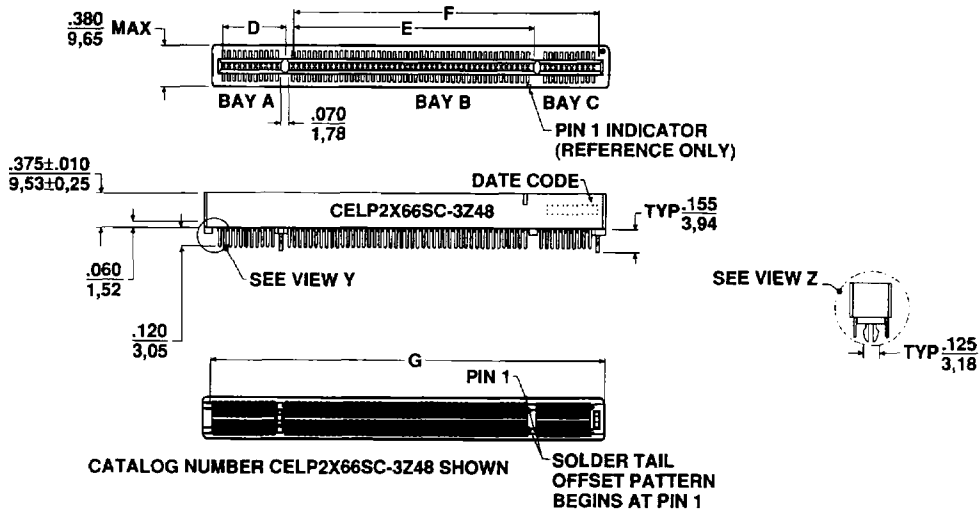
### MICROBUS: Low Profile Card Edge Connectors

Two-Bay Microbus™ Dimensions							
Burndy Catalog No.	Contacts Per Row	Contacts Per Row	No. of Contact Pairs		Inches (mm)		
			Bay A	Bay B	D	E	G
CELP2X56SC-3Z48	56	112	11	45	0.585 (14.86)	2.285 (58.04)	3.140 (79.76)
CELP2X60SC-3Z48	60	120	38	22	1.935 (49.15)	1.135 (28.83)	3.340 (84.84)
CELP2X80SC-3Z48	80	160	38	42	1.935 (49.15)	2.135 (54.23)	4.340 (110.24)
CELP2X82SC-3Z48	82	164	42	40	2.135 (54.23)	2.035 (51.69)	4.440 (112.78)
CELP2X91SC-12Z48	91	182	42	49	2.135 (54.23)	2.485 (63.12)	4.890 (124.21)



## MICROBUS: Low Profile Card Edge Connectors

Three-Bay Microbus™ Dimensions									
Burdny Catalog No.	Contacts Per Row	Contacts	No. of Contact Pairs			Inches (mm)			
		Per Row	Bay A	Bay B	Bay C	D	E	F	G
CELP2X66SC-3Z48	66	132	11	45	10	0.585 (14.86)	2.285 (58.12)	28.85 (73.28)	3.740 (94.97)
CELP2X92SC-3Z48	92	184	42	40	10	2.135 (54.23)	2.038 (51.77)	2.635 (66.93)	5.040 (128.02)
CELP2X80SC-3Z48	97	194	42	45	10	2.135 (54.23)	2.288 (58.12)	2.885 (73.28)	5.290 (134.37)
CELP2X82SC-3Z48	101	202	42	49	10	2.135 (54.23)	2.488 (63.20)	3.085 (78.36)	5.490 (139.45)
CELP2X91SC-12Z48	120	240	42	45	33	2.135 (54.23)	2.288 (58.12)	4.035 (102.49)	6.440 (163.58)



## MICROBUS Performance Characteristics

**Electrical:**

Contact Resistance: 30 milliohms max. initial, 10 milliohms max. increase through testing  
Current Rating: 0.5 ampere per contact  
Insulation Resistance: 1,000 megohms minimum

**Environmental:**

Operating Temperature: -13°F (-25°C) to 185°F (85°)

**Mechanical:**

Contact Normal Force: 2.12 oz (60 grams) minimum end of life  
Durability: 50 cycles as per Mil-C-21097 with standard daughtercard pad plating. (See alternate pad plating.)

**Material:**

Body: High temperature thermoplastic, UL 94V-0  
Contacts: Copper alloy  
Retention Clips: Steel alloy or phosphor bronze  
Component Board Materials:  
P.C. Board: FR-4 with 1 oz (28.35g) min. copper pads  
Pad Plating (standard): 30 microinches (0.76 microns) min. gold, per Mil-G-45204, Type 1, Class O, Grade C, over 100 microinches (2.54 microns) min. nickel per QQ-N-290  
Pad Plating (alternate): 10 microinches (0.25 microns) min. gold, per Mil-G-45204, Type 1, Class 1 (except 0.00001 thick), Grade C, over 150 microinches (3.81 microns) min. nickel per QQ-N-290

Recommended for cache memory module—Battelle class 1 environment only with 5 cycles max durability (insertion/withdrawal).

Connector also accepts 20° and 45° lead-in and blunt card edge boards (mating force may vary).

**Finish:**

Contact Plating: Gold flash over 25 microinches (0.64 microns) palladium nickel over 50 microinches (1.27 microns) nickel underplate in critical contact area and 75 microinches (1.91 microns) solder over nickel underplate on solder tails.